WHAT IS CLAIMED IS:

1. A protective tape attaching method for attaching a protective tape to a wafer, said protective tape having an adhesive layer formed on one side, said adhesive layer having adhesion to be reduced by applying ultraviolet light, said protective tape having a size corresponding to the size of said wafer, said protective tape attaching method comprising:

a bending step of bending a release paper to which said adhesive layer of said protective tape is previously attached, stretching said release paper to peel a front end portion of said protective tape from said release paper, and attaching said front end portion of said protective tape to said wafer;

an attaching step of pressing the other side of said protective tape opposite to said adhesive layer by using a pressure roller to thereby bring said adhesive layer of said protective tape into close contact with said wafer after performing said bending step, and further stretching said release paper to fully peel said protective tape from said release paper and attach the whole of said protective tape to said wafer; and

a peeling start point forming step of previously applying said ultraviolet light to said front end portion of said

protective tape to thereby reduce the adhesion of said adhesive layer of said front end portion of said protective tape before performing said bending step, thereby forming a peeling start point where peeling of said protective tape from said release paper is started, at said front end portion of said protective tape.